

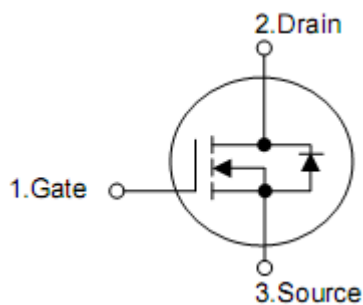
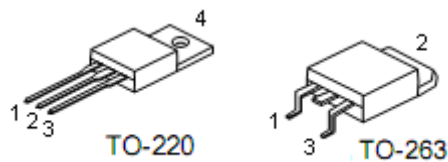
1. Features

- $V_{DSS}=70V / V_{GSS}=\pm 25V / I_D=80A, R_{DS(ON)}=10.8m\Omega(\text{Max.})@V_{GS}=10V$
- Avalanche Rated
- Reliable and Rugged
- Advanced trench process technology
- High Density Cell Design For Ultra Low On-Resistance

2. Applications

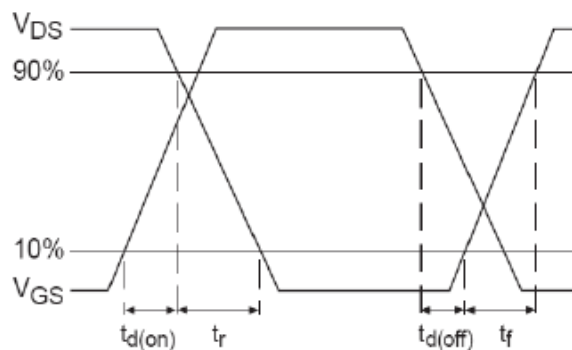
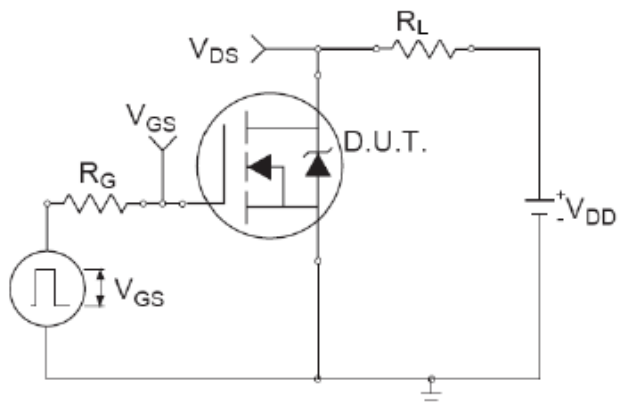
- Power Management in Inverter System

3. Pin configuration



Pin	Function
1	Gate
2	Drain
3	Source
4	Drain

4. Switching Time Test Circuit and Waveforms



5. Absolute maximum ratings

($T_A = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Rating	Units	
Drain-source voltage	V_{DSS}	70	V	
Gate-source voltage	V_{GSS}	± 25	V	
Drain current continuous	I_D	$T_C = 100^\circ\text{C}$	75	A
300 μs Pulsed drain current tested		$T_C = 25^\circ\text{C}$	80	A
Diode continuous forward current	I_S	300	A	
Operating junction temperature	T_J	80	A	
Storage temperature Range	T_{STG}	175	$^\circ\text{C}$	
		-55~175	$^\circ\text{C}$	

6. Electrical characteristics

(T_A=25°C, unless otherwise noted)

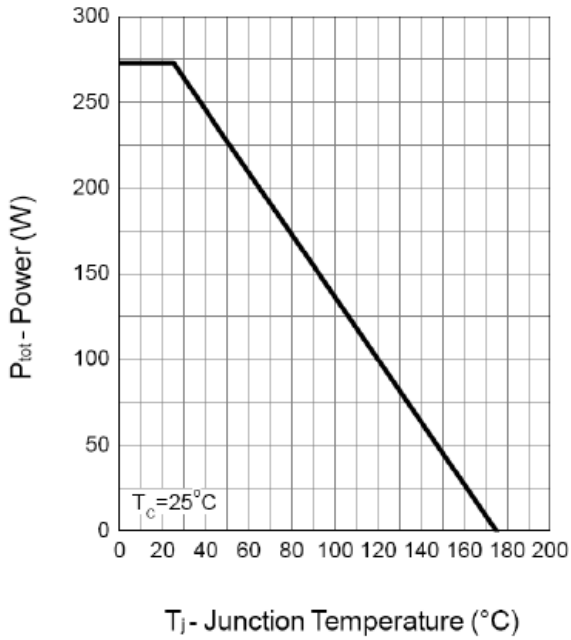
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	70	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =60V, V _{GS} =0V	-	-	1	μA
		T _J =85 °C	-	-	30	μA
Gate threshold voltage	V _{GS(TH)}	V _{DS} =V _{GS} , I _D =250μA	2	3	4	V
Gate leakage current	I _{GSS}	V _{GS} =±25V, V _{DS} =0V	-	-	±100	nA
Drain-source on-resistance	R _{DS(ON)}	V _{DS} =10V, I _D =40A	-	9	10.8	mΩ
Diode Characteristics						
Diode forward voltage	V _{SD}	I _{SD} =20A, V _{GS} =0V	-	0.8	1.1	V
Reverse recovery time	t _{RR}	I _{SD} =40A dI _{SD} /dt=100A/μs	-	55	-	ns
Reverse recovery charge	Q _{RR}		-	117	-	nC
Dynamic Characteristics						
Gate resistance	R _G	V _{DS} =0V, V _{GS} =0V Frequency=1MHz	-	1.5	-	Ω
Input capacitance	C _{ISS}	V _{DS} =30V, V _{GS} =0V, Frequency=1MHz	-	2200	-	pF
Output capacitance	C _{OSS}		-	470	-	pF
Reverse transfer capacitance	C _{RSS}		-	190	-	pF
Turn-on delay time	t _{D(ON)}		V _{DD} =15V, I _D =1.0A, R _L =15Ω V _{GEN} =-10V, R _G =6Ω,	-	23	42
Rise time	t _R	-		12	23	ns
Turn-off delay time	t _{D(OFF)}	-		77	140	ns
Fall time	t _F	-		69	125	ns
Gate Charge characteristics²						
Total gate charge	Q _G	V _{DS} =-15V, I _D =2.5A , V _{GS} =-4.5V	-	52	73	nC
Gate-source charge	Q _{GS}		-	19	-	nC
Gate-drain charge	Q _{GD}		-	27	-	nC

Notes:1:Pulse test;pulse width≤300ns,duty cycle≤2%.

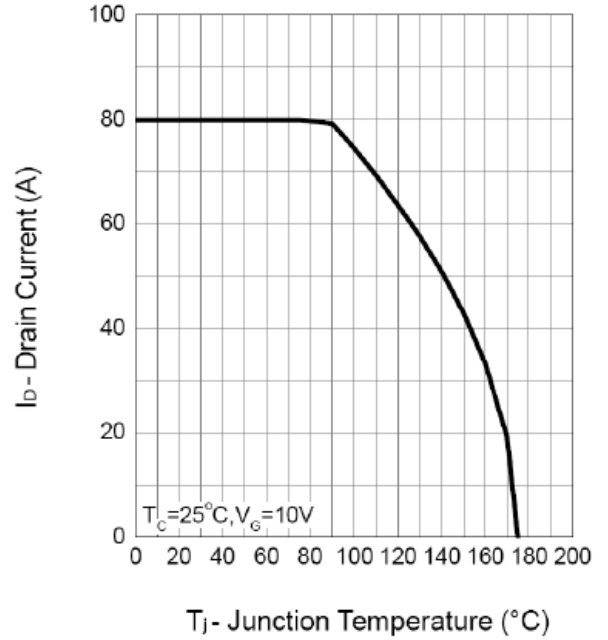
2:Guaranteed by design,not subject to production testing.

7. Test circuits and waveforms

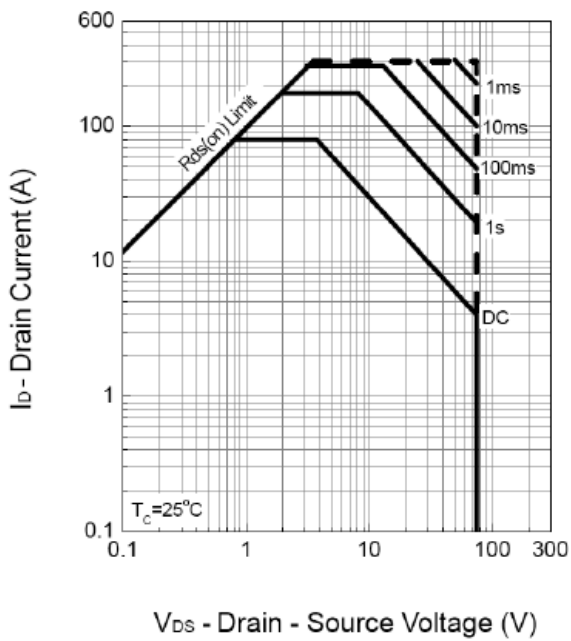
Power Dissipation



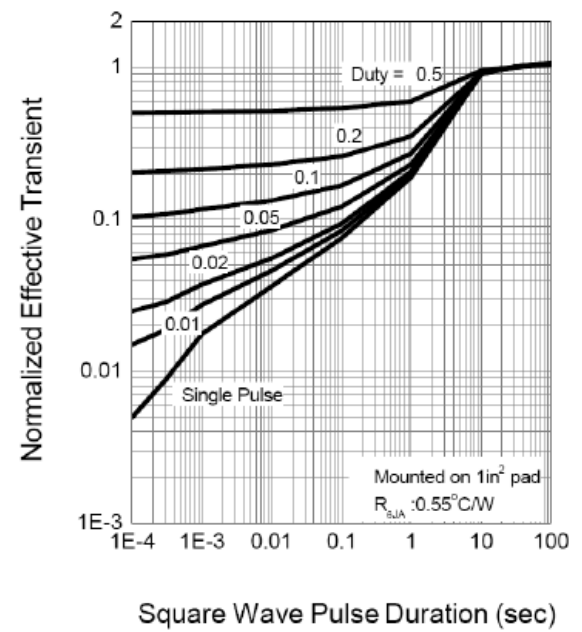
Drain Current



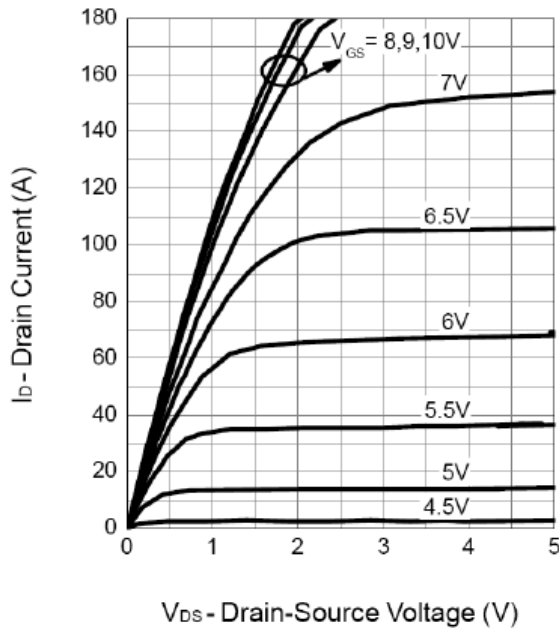
Safe Operation Area



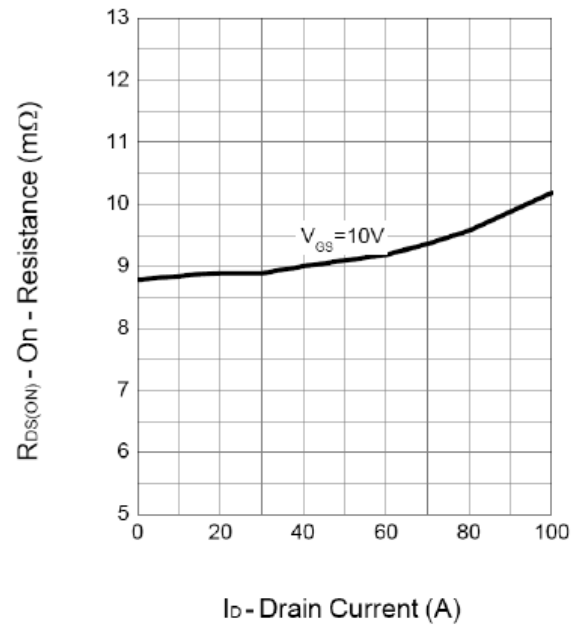
Thermal Transient Impedance



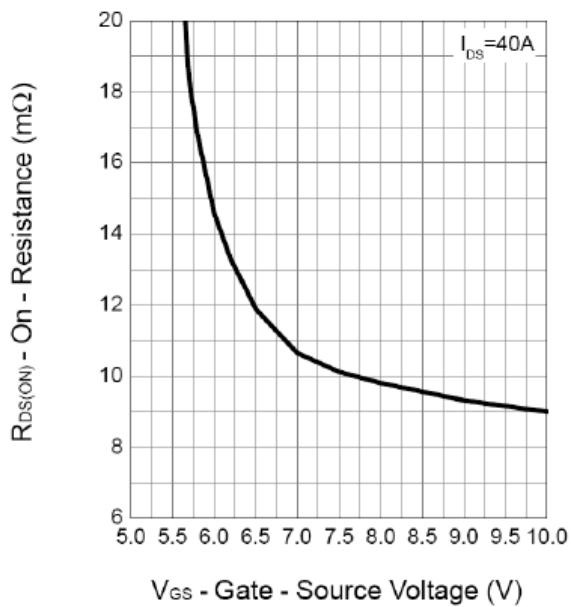
Output Characteristics



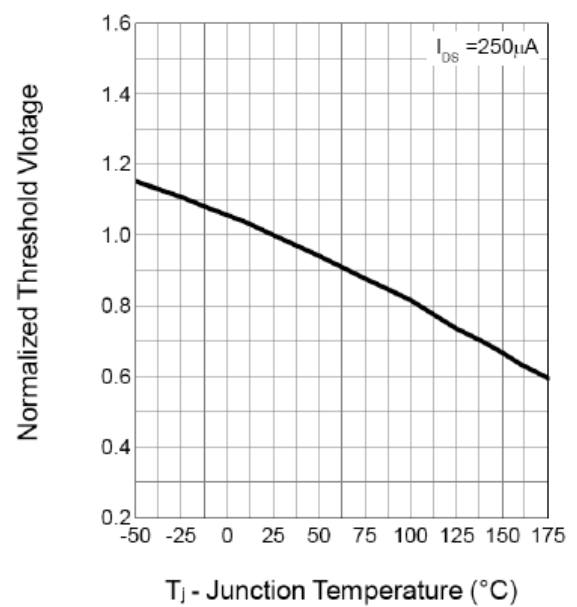
Drain-Source On Resistance



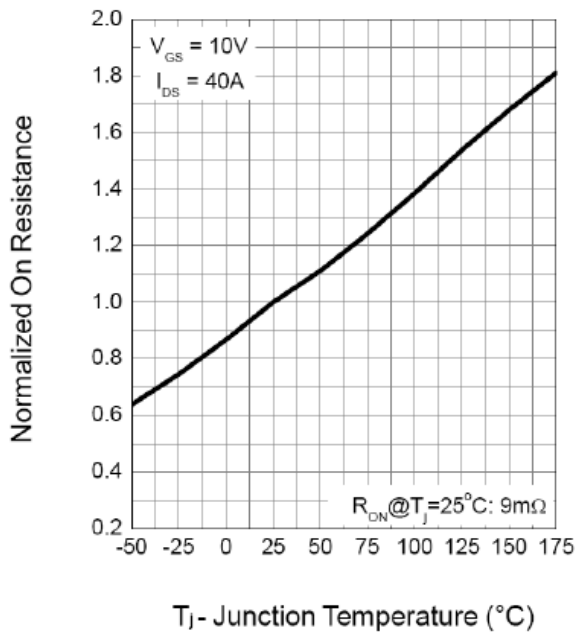
Gate-Source On Resistance



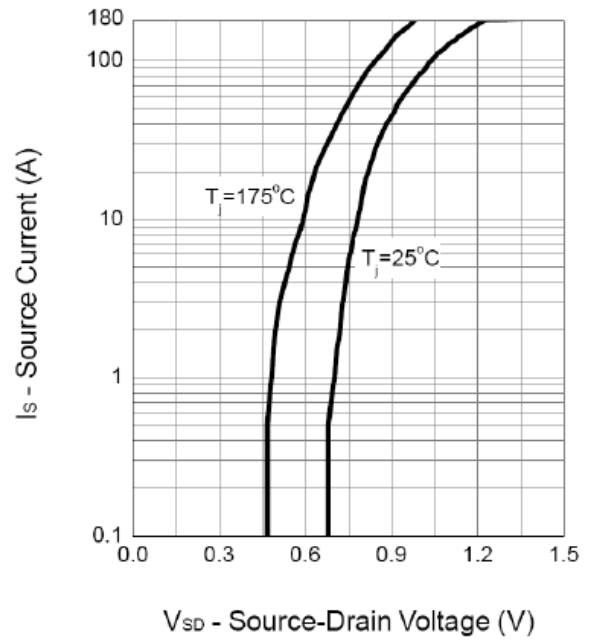
Gate Threshold Voltage



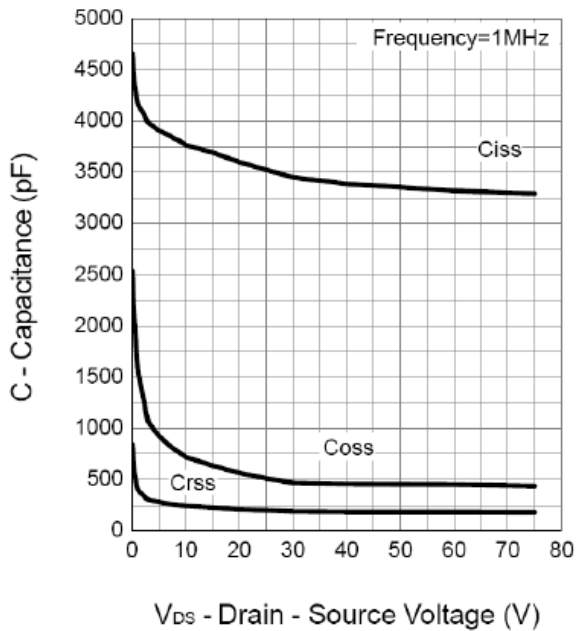
Drain-Source On Resistance



Source-Drain Diode Forward



Capacitance



Gate Charge

